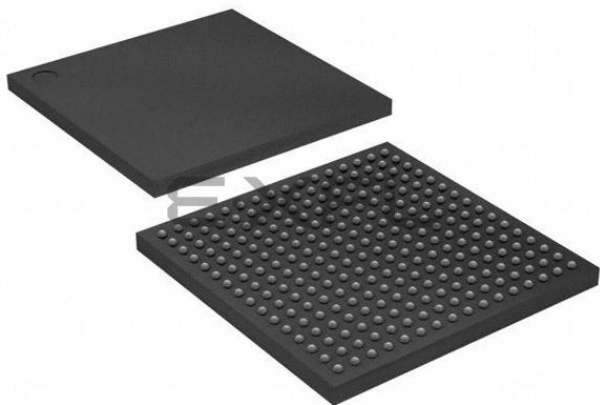




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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	64
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	88
Number of Gates	40000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2v40-4fgg256c

Shift Registers

Each function generator can also be configured as a 16-bit shift register. The write operation is synchronous with a clock input (CLK) and an optional clock enable, as shown in **Figure 21**. A dynamic read access is performed through the 4-bit address bus, A[3:0]. The configurable 16-bit shift register cannot be set or reset. The read is asynchronous, however the storage element or flip-flop is available to implement a synchronous read. The storage element should always be used with a constant address. For example, when building an 8-bit shift register and configuring the addresses to point to the 7th bit, the 8th bit can be the flip-flop. The overall system performance is improved by using the superior clock-to-out of the flip-flops.

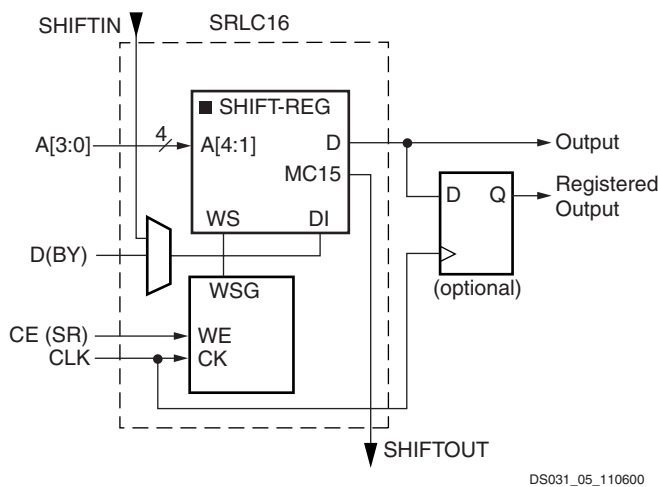


Figure 21: Shift Register Configurations

An additional dedicated connection between shift registers allows connecting the last bit of one shift register to the first bit of the next, without using the ordinary LUT output. (See **Figure 22**.) Longer shift registers can be built with dynamic access to any bit in the chain. The shift register chaining and the MUXF5, MUXF6, and MUXF7 multiplexers allow up to a 128-bit shift register with addressable access to be implemented in one CLB.

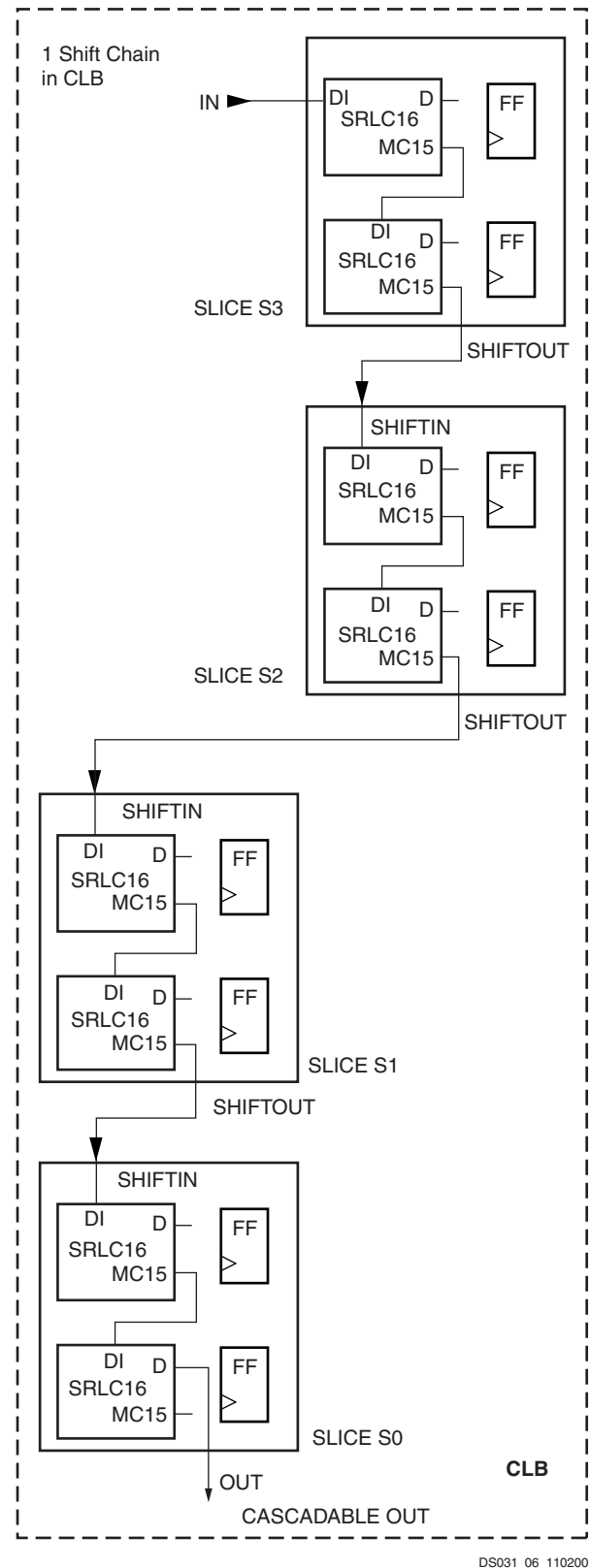


Figure 22: Cascadable Shift Register

Table 5: Minimum Power On Current Required for Virtex-II Devices

	Device (mA)							
	XC2V40, XC2V80, XC2V250, XC2V500	XC2V1000	XC2V1500	XC2V2000	XC2V3000	XC2V4000	XC2V6000	XC2V8000
$I_{CCINTMIN}$	200	250	350	400	500	650	800	1100
$I_{CCAUXMIN}$	100	100	100	100	100	100	100	100
I_{CCOMIN}	50	50	100	100	100	100	100	100

Notes:

- Values specified for power on current parameters are Commercial Grade. For Industrial Grade values, multiply Commercial Grade values by 1.25.
- I_{CCOMIN} values listed here apply to the entire device (all banks).

General Power Supply Requirements

Proper decoupling of all FPGA power supplies is essential. Consult Xilinx Application Note [XAPP623](#) for detailed information on power distribution system design.

V_{CCAUX} powers critical resources in the FPGA. Thus, V_{CCAUX} is especially susceptible to power supply noise.

Changes in V_{CCAUX} voltage outside of 200 mV peak to peak should take place at a rate no faster than 10 mV per millisecond. Techniques to help reduce jitter and period distortion are provided in Xilinx Answer Record 13756, available at [www.support.xilinx.com](#).

V_{CCAUX} can share a power plane with 3.3V V_{CCO} , but only if V_{CCO} does not have excessive noise. Using simultaneously switching output (SSO) limits are essential for keeping power supply noise to a minimum. Refer to [XAPP689](#), "Managing Ground Bounce in Large FPGAs," to determine the number of simultaneously switching outputs allowed per bank at the package level.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Table 6: DC Input and Output Levels

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL ⁽¹⁾	-0.5	0.8	2.0	3.6	0.4	2.4	24	-24
LVC MOS33	-0.5	0.8	2.0	3.6	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS25	-0.5	0.7	1.7	2.7	0.4	$V_{CCO} - 0.4$	24	-24
LVC MOS18	-0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	$V_{CCO} - 0.4$	16	-16
LVC MOS15	-0.5	35% V_{CCO}	65% V_{CCO}	1.7	0.4	$V_{CCO} - 0.4$	16	-16
PCI33_3	-0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
PCI66_3	-0.5	30% V_{CCO}	50% V_{CCO}	$V_{CCO} + 0.5$	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
PCI-X	-0.5	Note 2	Note 2	Note 2	Note 2	Note 2	Note 2	Note 2
GTLP	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.6	n/a	36	n/a
GTL	-0.5	$V_{REF} - 0.05$	$V_{REF} + 0.05$	$V_{CCO} + 0.5$	0.4	n/a	40	n/a
HSTL I	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	8	-8
HSTL II	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	16	-16
HSTL III	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	24	-8
HSTL IV	-0.5	$V_{REF} - 0.1$	$V_{REF} + 0.1$	$V_{CCO} + 0.5$	0.4	$V_{CCO} - 0.4$	48	-8

Virtex-II Switching Characteristics

Switching characteristics in this document are specified on a per-speed-grade basis and can be designated as Advance, Preliminary, or Production. Note that **Virtex-II Performance Characteristics, page 7** are subject to these guidelines as well. Each designation is defined as follows:

Advance: These speed files are based on simulations only and are typically available soon after device design specifications are frozen. Although speed grades with this designation are considered relatively stable and conservative, some under-reporting might still occur.

Preliminary: These speed files are based on complete ES (engineering sample) silicon characterization. Devices and speed grades with this designation are intended to give a better indication of the expected performance of production silicon. The probability of under-reporting delays is greatly reduced as compared to Advance data.

Production: These speed files are released once enough production silicon of a particular device family member has been characterized to provide full correlation between speed files and devices over numerous production lots. There is no under-reporting of delays, and customers receive formal notification of any subsequent changes. Typically, the slowest speed grades transition to Production before faster speed grades.

Since individual family members are produced at different times, the migration from one category to another depends completely on the status of the fabrication process for each device. **Table 13** correlates the current status of each Virtex-II device with a corresponding speed grade designation.

All specifications are always representative of worst-case supply voltage and junction temperature conditions.

Testing of Switching Characteristics

All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the Xilinx static timing analyzer and back-annotate to the simulation net list. Unless otherwise noted, values apply to all Virtex-II devices.

IOB Input Switching Characteristics

Input delays associated with the pad are specified for LVTTTL levels. For other standards, adjust the delays with the values shown in **IOB Input Switching Characteristics Standard Adjustments, page 11**.

Table 13: Virtex-II Device Speed Grade Designations

Device	Speed Grade Designations		
	Advance	Preliminary	Production
XC2V40			-6, -5, -4
XC2V80			-6, -5, -4
XC2V250			-6, -5, -4
XC2V500			-6, -5, -4
XC2V1000			-6, -5, -4
XC2V1500			-6, -5, -4
XC2V2000			-6, -5, -4
XC2V3000			-6, -5, -4
XC2V4000			-6, -5, -4
XC2V6000			-6, -5, -4
XC2V8000			-5, -4

Table 14: IOB Input Switching Characteristics

			Speed Grade			Units
Description	Symbol	Device	-6	-5	-4	
Propagation Delays						
Pad to I output, no delay	T _{IOPi}	All	0.69	0.76	0.88	ns, Max
Pad to I output, with delay	T _{IOPID}	XC2V40	1.92	2.11	2.43	ns, Max
		XC2V80	1.92	2.11	2.43	ns, Max
		XC2V250	1.92	2.11	2.43	ns, Max
		XC2V500	1.92	2.11	2.43	ns, Max
		XC2V1000	1.92	2.11	2.43	ns, Max
		XC2V1500	1.92	2.11	2.43	ns, Max
		XC2V2000	1.92	2.11	2.43	ns, Max
		XC2V3000	1.97	2.16	2.49	ns, Max
		XC2V4000	1.97	2.16	2.49	ns, Max
		XC2V6000	2.10	2.31	2.66	ns, Max
		XC2V8000		2.31	2.66	ns, Max

I/O Standard Adjustment Measurement Methodology

Input Delay Measurements

Table 18 shows the test setup parameters used for measuring Input standard adjustments (see Table 15, page 11).

Table 18: Input Delay Measurement Methodology

Description	IOSTANDARD Attribute	$V_L^{(1,2)}$	$V_H^{(1,2)}$	$V_{MEAS}^{(1,4,5)}$	$V_{REF}^{(1,3,5)}$
LVTTL (Low-Voltage Transistor-Transistor Logic)	LVTTL	0	3.0	1.4	–
LVC MOS (Low-Voltage CMOS), 3.3V	LVC MOS33	0	3.3	1.65	–
LVC MOS, 2.5V	LVC MOS25	0	2.5	1.25	–
LVC MOS, 1.8V	LVC MOS18	0	1.8	0.9	–
LVC MOS, 1.5V	LVC MOS15	0	1.5	0.75	–
PCI (Peripheral Component Interface), 33 MHz, 3.3V	PCI33_3	Per PCI Specification			–
PCI, 66 MHz, 3.3V	PCI66_3	Per PCI Specification			–
PCI-X, 133 MHz, 3.3V	PCIX	Per PCI-X Specification			–
GTL (Gunning Transceiver Logic)	GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.80
GTL Plus	GTL P	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.0
HSTL (High-Speed Transceiver Logic), Class I & II	HSTL_I, HSTL_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL, Class III & IV	HSTL_III, HSTL_IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class I & II, 1.8V	HSTL_I_18, HSTL_II_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL, Class III & IV, 1.8V	HSTL_III_18, HSTL_IV_18	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	1.08
SSTL (Stub Terminated Transceiver Logic), Class I & II, 3.3V	SSTL3_I, SSTL3_II	$V_{REF} - 1.00$	$V_{REF} + 1.00$	V_{REF}	1.5
SSTL, Class I & II, 2.5V	SSTL2_I, SSTL2_II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
SSTL, Class I & II, 1.8V	SSTL18_I, SSTL18_II	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
AGP-2X/AGP (Accelerated Graphics Port)	AGP	$V_{REF} - (0.2 \times V_{CCO})$	$V_{REF} + (0.2 \times V_{CCO})$	V_{REF}	AGP Spec
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
LVDS, 3.3V	LVDS_33	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
LVDSEXT, 3.3V	LVDSEXT_33	$1.2 - 0.125$	$1.2 + 0.125$	1.2	
ULVDS (Ultra LVDS), 2.5V	ULVDS_25	$0.6 - 0.125$	$0.6 + 0.125$	0.6	
LDT (HyperTransport), 2.5V	LDT_25	$0.6 - 0.125$	$0.6 + 0.125$	0.6	
LVPECL (Low-Voltage Positive Electron-Coupled Logic), 3.3V	LVPECL_33	$1.6 - 0.3$	$1.6 + 0.3$	1.6	

Notes:

- Input delay measurement methodology parameters for LVDCI and HSLVDCI are the same as for LVC MOS standards of the same voltage. Parameters for all other DCI standards are the same as for the corresponding non-DCI standards.
- Input waveform switches between V_L and V_H .
- Measurements are made at typical, minimum, and maximum V_{REF} values. Reported delays reflect worst case of these measurements. V_{REF} values listed are typical. See [Virtex-II Platform FPGA User Guide](#) for min/max specifications.
- Input voltage level from which measurement starts.
- Note that this is an input voltage reference that bears no relation to the V_{REF} / V_{MEAS} parameters found in IBIS models and/or noted in Figure 1.

Table 27: Enhanced Pipelined Multiplier Switching Characteristics

Description	Symbol	Speed Grade			Units
		-6	-5	-4	
Setup and Hold Times Before/After Clock					
Data Inputs	T _{MULIDCK} /T _{MULCKID}	3.00/0.00	3.45/0.00	3.89/0.00	ns, Max
Clock Enable	T _{MULIDCK_CE} /T _{MULCKID_CE}	0.72/0.00	0.80/0.00	0.86/0.00	ns, Max
Reset	T _{MULIDCK_RST} /T _{MULCKID_RST}	0.72/0.00	0.80/0.00	0.86/0.00	ns, Max
Clock to Output Pin					
Clock to Pin 35	T _{MULTCK1_P35}	3.05	3.25	3.74	ns, Max
Clock to Pin 34	T _{MULTCK1_P34}	2.95	3.14	3.61	ns, Max
Clock to Pin 33	T _{MULTCK1_P33}	2.85	3.04	3.49	ns, Max
Clock to Pin 32	T _{MULTCK1_P32}	2.76	2.93	3.37	ns, Max
Clock to Pin 31	T _{MULTCK1_P31}	2.66	2.82	3.25	ns, Max
Clock to Pin 30	T _{MULTCK1_P30}	2.56	2.72	3.12	ns, Max
Clock to Pin 29	T _{MULTCK1_P29}	2.47	2.61	3.00	ns, Max
Clock to Pin 28	T _{MULTCK1_P28}	2.37	2.50	2.88	ns, Max
Clock to Pin 27	T _{MULTCK1_P27}	2.27	2.40	2.75	ns, Max
Clock to Pin 26	T _{MULTCK1_P26}	2.17	2.29	2.63	ns, Max
Clock to Pin 25	T _{MULTCK1_P25}	2.08	2.18	2.51	ns, Max
Clock to Pin 24	T _{MULTCK1_P24}	1.98	2.07	2.38	ns, Max
Clock to Pin 23	T _{MULTCK1_P23}	1.88	1.97	2.26	ns, Max
Clock to Pin 22	T _{MULTCK1_P22}	1.79	1.86	2.14	ns, Max
Clock to Pin 21	T _{MULTCK1_P21}	1.69	1.75	2.02	ns, Max
Clock to Pin 20	T _{MULTCK1_P20}	1.59	1.65	1.89	ns, Max
Clock to Pin 19	T _{MULTCK1_P19}	1.50	1.54	1.77	ns, Max
Clock to Pin 18	T _{MULTCK1_P18}	1.40	1.43	1.65	ns, Max
Clock to Pin 17	T _{MULTCK1_P17}	1.30	1.33	1.52	ns, Max
Clock to Pin 16	T _{MULTCK1_P16}	1.20	1.22	1.40	ns, Max
Clock to Pin 15	T _{MULTCK1_P15}	1.11	1.11	1.28	ns, Max
Clock to Pin 14	T _{MULTCK1_P14}	1.01	1.00	1.15	ns, Max
Clock to Pin 13	T _{MULTCK1_P13}	0.91	1.00	1.15	ns, Max
Clock to Pin 12	T _{MULTCK1_P12}	0.91	1.00	1.15	ns, Max
Clock to Pin 11	T _{MULTCK1_P11}	0.91	1.00	1.15	ns, Max
Clock to Pin 10	T _{MULTCK1_P10}	0.91	1.00	1.15	ns, Max
Clock to Pin 9	T _{MULTCK1_P9}	0.91	1.00	1.15	ns, Max
Clock to Pin 8	T _{MULTCK1_P8}	0.91	1.00	1.15	ns, Max
Clock to Pin 7	T _{MULTCK1_P7}	0.91	1.00	1.15	ns, Max
Clock to Pin 6	T _{MULTCK1_P6}	0.91	1.00	1.15	ns, Max
Clock to Pin 5	T _{MULTCK1_P5}	0.91	1.00	1.15	ns, Max
Clock to Pin 4	T _{MULTCK1_P4}	0.91	1.00	1.15	ns, Max
Clock to Pin 3	T _{MULTCK1_P3}	0.91	1.00	1.15	ns, Max
Clock to Pin 2	T _{MULTCK1_P2}	0.91	1.00	1.15	ns, Max
Clock to Pin 1	T _{MULTCK1_P1}	0.91	1.00	1.15	ns, Max
Clock to Pin 0	T _{MULTCK1_P0}	0.91	1.00	1.15	ns, Max

Table 7: FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
2	IO_L45N_2	H19		
2	IO_L45P_2/VREF_2	H20		
2	IO_L46N_2	H21		
2	IO_L46P_2	H22		
2	IO_L48N_2	J17		
2	IO_L48P_2	J18		
2	IO_L49N_2	J19	NC	
2	IO_L49P_2	J20	NC	
2	IO_L51N_2	J21	NC	
2	IO_L51P_2/VREF_2	J22	NC	
2	IO_L52N_2	K17	NC	
2	IO_L52P_2	K18	NC	
2	IO_L54N_2	K19	NC	
2	IO_L54P_2	K20	NC	
2	IO_L91N_2	K21		
2	IO_L91P_2	K22		
2	IO_L93N_2	L17		
2	IO_L93P_2/VREF_2	L18		
2	IO_L94N_2	L19		
2	IO_L94P_2	L20		
2	IO_L96N_2	L21		
2	IO_L96P_2	L22		
3	IO_L96N_3	M21		
3	IO_L96P_3	M20		
3	IO_L94N_3	M19		
3	IO_L94P_3	M18		
3	IO_L93N_3/VREF_3	M17		
3	IO_L93P_3	N17		
3	IO_L91N_3	N22		
3	IO_L91P_3	N21		
3	IO_L54N_3	N20	NC	
3	IO_L54P_3	N19	NC	
3	IO_L52N_3	N18	NC	

Table 7: FG456/FGG456 BGA — XC2V250, XC2V500, and XC2V1000

Bank	Pin Description	Pin Number	No Connect in XC2V250	No Connect in XC2V500
7	IO_L51N_7	J2	NC	
7	IO_L49P_7	J3	NC	
7	IO_L49N_7	J4	NC	
7	IO_L48P_7	H1		
7	IO_L48N_7	H2		
7	IO_L46P_7	H3		
7	IO_L46N_7	H4		
7	IO_L45P_7/VREF_7	J6		
7	IO_L45N_7	H5		
7	IO_L43P_7	G1		
7	IO_L43N_7	G2		
7	IO_L24P_7	G3	NC	NC
7	IO_L24N_7	G4	NC	NC
7	IO_L22P_7	F1	NC	NC
7	IO_L22N_7	F2	NC	NC
7	IO_L21P_7/VREF_7	F3	NC	NC
7	IO_L21N_7	F4	NC	NC
7	IO_L19P_7	G5	NC	NC
7	IO_L19N_7	F5	NC	NC
7	IO_L06P_7	E1		
7	IO_L06N_7	E2		
7	IO_L04P_7	E3		
7	IO_L04N_7	E4		
7	IO_L03P_7/VREF_7	D1		
7	IO_L03N_7	D2		
7	IO_L02P_7/VRN_7	C1		
7	IO_L02N_7/VRP_7	C2		
7	IO_L01P_7	E5		
7	IO_L01N_7	E6		
0	VCCO_0	G11		
0	VCCO_0	G10		
0	VCCO_0	G9		
0	VCCO_0	F8		

FG676/FGG676 Fine-Pitch BGA Package

As shown in Table 8, XC2V1500, XC2V2000, and XC2V3000 Virtex-II devices are available in the FG676/FGG676 fine-pitch BGA package. Pins in the XC2V1500, XC2V2000, and XC2V3000 devices are the same, except for the pin differences in the XC2V1500 and XC2V2000 devices shown in the No Connect columns. Following this table are the **FG676/FGG676 Fine-Pitch BGA Package Specifications (1.00mm pitch)**.

Table 8: FG676/FGG676 BGA — XC2V1500, XC2V2000, and XC2V3000

Bank	Pin Description	Pin Number	No Connect in XC2V1500	No Connect in XC2V2000
0	IO_L01N_0	D6		
0	IO_L01P_0	C6		
0	IO_L02N_0	B1		
0	IO_L02P_0	A2		
0	IO_L03N_0/VRP_0	D7		
0	IO_L03P_0/VRN_0	C7		
0	IO_L04N_0/VREF_0	B3		
0	IO_L04P_0	A3		
0	IO_L05N_0	G6		
0	IO_L05P_0	G7		
0	IO_L06N_0	E6		
0	IO_L06P_0	E7		
0	IO_L19N_0	B4		
0	IO_L19P_0	A4		
0	IO_L21N_0	B5		
0	IO_L21P_0/VREF_0	A5		
0	IO_L22N_0	B6		
0	IO_L22P_0	A6		
0	IO_L24N_0	A7		
0	IO_L24P_0	A8		
0	IO_L25N_0	E8	NC	NC
0	IO_L25P_0	D8	NC	NC
0	IO_L27N_0	G8	NC	NC
0	IO_L27P_0/VREF_0	F8	NC	NC
0	IO_L49N_0	C8		
0	IO_L49P_0	B8		
0	IO_L51N_0	D9		
0	IO_L51P_0/VREF_0	E9		
0	IO_L52N_0	F9		
0	IO_L52P_0	G9		
0	IO_L54N_0	B9		
0	IO_L54P_0	A9		
0	IO_L67N_0	C9		

Table 10: BG728 BGA — XC2V3000

Bank	Pin Description	Pin Number
4	IO_L27P_4/VREF_4	AG19
4	IO_L28N_4	AB19
4	IO_L28P_4	AA19
4	IO_L30N_4	AC19
4	IO_L30P_4	AD19
4	IO_L49N_4	AE19
4	IO_L49P_4	AF19
4	IO_L51N_4	AA18
4	IO_L51P_4/VREF_4	Y18
4	IO_L52N_4	AB18
4	IO_L52P_4	AC18
4	IO_L54N_4	AD18
4	IO_L54P_4	AE18
4	IO_L67N_4	AF18
4	IO_L67P_4	AG18
4	IO_L69N_4	AA17
4	IO_L69P_4/VREF_4	Y17
4	IO_L70N_4	AB17
4	IO_L70P_4	AB16
4	IO_L72N_4	AD17
4	IO_L72P_4	AE17
4	IO_L73N_4	AF17
4	IO_L73P_4	AG17
4	IO_L75N_4	Y16
4	IO_L75P_4/VREF_4	W16
4	IO_L76N_4	AC16
4	IO_L76P_4	AD16
4	IO_L78N_4	AF16
4	IO_L78P_4	AG16
4	IO_L91N_4/VREF_4	W15
4	IO_L91P_4	Y15
4	IO_L92N_4	AB15
4	IO_L92P_4	AA15
4	IO_L93N_4	AC15
4	IO_L93P_4	AD15
4	IO_L94N_4/VREF_4	AE15

Table 10: BG728 BGA — XC2V3000

Bank	Pin Description	Pin Number
6	IO_L52N_6	V3
6	IO_L54P_6	V2
6	IO_L54N_6	V1
6	IO_L67P_6	U8
6	IO_L67N_6	T8
6	IO_L69P_6	U6
6	IO_L69N_6/VREF_6	U7
6	IO_L70P_6	U4
6	IO_L70N_6	U3
6	IO_L72P_6	U2
6	IO_L72N_6	U1
6	IO_L73P_6	T9
6	IO_L73N_6	R9
6	IO_L75P_6	T5
6	IO_L75N_6/VREF_6	T6
6	IO_L76P_6	T4
6	IO_L76N_6	R4
6	IO_L78P_6	T2
6	IO_L78N_6	T1
6	IO_L91P_6	R7
6	IO_L91N_6	R8
6	IO_L93P_6	R5
6	IO_L93N_6/VREF_6	R6
6	IO_L94P_6	R3
6	IO_L94N_6	P3
6	IO_L96P_6	R2
6	IO_L96N_6	R1
7	IO_L96P_7	P5
7	IO_L96N_7	P6
7	IO_L94P_7	P7
7	IO_L94N_7	P8
7	IO_L93P_7/VREF_7	N1
7	IO_L93N_7	N2
7	IO_L91P_7	N3
7	IO_L91N_7	N4

Table 10: BG728 BGA — XC2V3000

Bank	Pin Description	Pin Number
NA	VCCAUX	P26
NA	VCCAUX	P2
NA	VCCAUX	C26
NA	VCCAUX	C2
NA	VCCAUX	B14
NA	VCCINT	V18
NA	VCCINT	V14
NA	VCCINT	V10
NA	VCCINT	U17
NA	VCCINT	U16
NA	VCCINT	U15
NA	VCCINT	U14
NA	VCCINT	U13
NA	VCCINT	U12
NA	VCCINT	U11
NA	VCCINT	T17
NA	VCCINT	T11
NA	VCCINT	R17
NA	VCCINT	R11
NA	VCCINT	P18
NA	VCCINT	P17
NA	VCCINT	P11
NA	VCCINT	P10
NA	VCCINT	N17
NA	VCCINT	N11
NA	VCCINT	M17
NA	VCCINT	M11
NA	VCCINT	L17
NA	VCCINT	L16
NA	VCCINT	L15
NA	VCCINT	L14
NA	VCCINT	L13
NA	VCCINT	L12
NA	VCCINT	L11
NA	VCCINT	K18
NA	VCCINT	K14

Table 11: FF896 BGA — XC2V1000, XC2V1500, and XC2V2000

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
4	IO_L73P_4	AJ12	NC	NC
4	IO_L74N_4	AE13	NC	NC
4	IO_L74P_4	AE14	NC	NC
4	IO_L75N_4	AF13	NC	NC
4	IO_L75P_4/VREF_4	AG13	NC	NC
4	IO_L76N_4	AK13	NC	NC
4	IO_L76P_4	AK12	NC	NC
4	IO_L77N_4	AB14	NC	NC
4	IO_L77P_4	AB15	NC	NC
4	IO_L78N_4	AF15	NC	NC
4	IO_L78P_4	AF14	NC	NC
4	IO_L91N_4/VREF_4	AJ14		
4	IO_L91P_4	AJ15		
4	IO_L92N_4	AC14		
4	IO_L92P_4	AC15		
4	IO_L93N_4	AG15		
4	IO_L93P_4	AG14		
4	IO_L94N_4/VREF_4	AK14		
4	IO_L94P_4	AK15		
4	IO_L95N_4/GCLK3S	AD15		
4	IO_L95P_4/GCLK2P	AE15		
4	IO_L96N_4/GCLK1S	AH14		
4	IO_L96P_4/GCLK0P	AH15		
5	IO_L96N_5/GCLK7S	AH16		
5	IO_L96P_5/GCLK6P	AH17		
5	IO_L95N_5/GCLK5S	AE16		
5	IO_L95P_5/GCLK4P	AD16		
5	IO_L94N_5	AJ16		
5	IO_L94P_5/VREF_5	AJ17		
5	IO_L93N_5	AG17		
5	IO_L93P_5	AG16		
5	IO_L92N_5	AC16		
5	IO_L92P_5	AC17		
5	IO_L91N_5	AK17		
5	IO_L91P_5/VREF_5	AK18		
5	IO_L78N_5	AF17	NC	NC

Table 11: FF896 BGA — XC2V1000, XC2V1500, and XC2V2000

Bank	Pin Description	Pin Number	No Connect in the XC2V1000	No Connect in the XC2V1500
NA	VCCINT	N20		
NA	VCCINT	N11		
NA	VCCINT	M20		
NA	VCCINT	M11		
NA	VCCINT	L20		
NA	VCCINT	L19		
NA	VCCINT	L18		
NA	VCCINT	L17		
NA	VCCINT	L16		
NA	VCCINT	L15		
NA	VCCINT	L14		
NA	VCCINT	L13		
NA	VCCINT	L12		
NA	VCCINT	L11		
NA	VCCINT	K21		
NA	VCCINT	K10		
NA	VCCINT	J22		
NA	VCCINT	J9		
NA	GND	AK23		
NA	GND	AK8		
NA	GND	AJ29		
NA	GND	AJ2		
NA	GND	AH28		
NA	GND	AH21		
NA	GND	AH10		
NA	GND	AH3		
NA	GND	AG27		
NA	GND	AG4		
NA	GND	AF26		
NA	GND	AF19		
NA	GND	AF12		
NA	GND	AF5		
NA	GND	AE25		
NA	GND	AE6		
NA	GND	AD17		
NA	GND	AD14		
NA	GND	AC30		

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
0	IO_L77N_0	J20	
0	IO_L77P_0	K19	
0	IO_L78N_0	D20	
0	IO_L78P_0	D21	
0	IO_L79N_0	A21	NC
0	IO_L79P_0	A22	NC
0	IO_L80N_0	L19	NC
0	IO_L80P_0	L18	NC
0	IO_L81N_0	B19	NC
0	IO_L81P_0/VREF_0	A20	NC
0	IO_L82N_0	A18	NC
0	IO_L82P_0	B18	NC
0	IO_L83N_0	H19	NC
0	IO_L83P_0	H18	NC
0	IO_L84N_0	C20	NC
0	IO_L84P_0	C21	NC
0	IO_L91N_0/VREF_0	D19	
0	IO_L91P_0	D18	
0	IO_L92N_0	G18	
0	IO_L92P_0	G19	
0	IO_L93N_0	F18	
0	IO_L93P_0	F19	
0	IO_L94N_0/VREF_0	C19	
0	IO_L94P_0	C18	
0	IO_L95N_0/GCLK7P	K18	
0	IO_L95P_0/GCLK6S	J18	
0	IO_L96N_0/GCLK5P	E19	
0	IO_L96P_0/GCLK4S	E18	
1	IO_L96N_1/GCLK3P	E17	
1	IO_L96P_1/GCLK2S	E16	
1	IO_L95N_1/GCLK1P	H17	
1	IO_L95P_1/GCLK0S	H16	
1	IO_L94N_1	D17	
1	IO_L94P_1/VREF_1	D16	
1	IO_L93N_1	F16	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
1	IO_L93P_1	F17	
1	IO_L92N_1	G16	
1	IO_L92P_1	G17	
1	IO_L91N_1	C16	
1	IO_L91P_1/VREF_1	C15	
1	IO_L84N_1	D14	NC
1	IO_L84P_1	D15	NC
1	IO_L83N_1	J17	NC
1	IO_L83P_1	K17	NC
1	IO_L82N_1	B17	NC
1	IO_L82P_1	A17	NC
1	IO_L81N_1/VREF_1	A15	NC
1	IO_L81P_1	B16	NC
1	IO_L80N_1	L17	NC
1	IO_L80P_1	L16	NC
1	IO_L79N_1	A13	NC
1	IO_L79P_1	A14	NC
1	IO_L78N_1	C13	
1	IO_L78P_1	C14	
1	IO_L77N_1	K16	
1	IO_L77P_1	K15	
1	IO_L76N_1	B13	
1	IO_L76P_1	B14	
1	IO_L75N_1/VREF_1	F15	
1	IO_L75P_1	G15	
1	IO_L74N_1	H15	
1	IO_L74P_1	H14	
1	IO_L73N_1	A11	
1	IO_L73P_1	A12	
1	IO_L72N_1	E13	
1	IO_L72P_1	E14	
1	IO_L71N_1	J15	
1	IO_L71P_1	J14	
1	IO_L70N_1	D12	
1	IO_L70P_1	D13	
1	IO_L69N_1/VREF_1	F14	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
4	IO_L20N_4	AJ10	
4	IO_L20P_4	AJ9	
4	IO_L21N_4	AH9	
4	IO_L21P_4/VREF_4	AH10	
4	IO_L22N_4	AN5	
4	IO_L22P_4	AN4	
4	IO_L23N_4	AE12	
4	IO_L23P_4	AE13	
4	IO_L24N_4	AM9	
4	IO_L24P_4	AL8	
4	IO_L25N_4	AP5	
4	IO_L25P_4	AP4	
4	IO_L26N_4	AG11	
4	IO_L26P_4	AG12	
4	IO_L27N_4	AN7	
4	IO_L27P_4/VREF_4	AN6	
4	IO_L28N_4	AL10	
4	IO_L28P_4	AL9	
4	IO_L29N_4	AF12	
4	IO_L29P_4	AF13	
4	IO_L30N_4	AK10	
4	IO_L30P_4	AK11	
4	IO_L49N_4	AP7	
4	IO_L49P_4	AP6	
4	IO_L50N_4	AH13	
4	IO_L50P_4	AH12	
4	IO_L51N_4	AJ11	
4	IO_L51P_4/VREF_4	AJ12	
4	IO_L52N_4	AP9	
4	IO_L52P_4	AN8	
4	IO_L53N_4	AG13	
4	IO_L53P_4	AG14	
4	IO_L54N_4	AM11	
4	IO_L54P_4	AL11	
4	IO_L60N_4	AN10	NC
4	IO_L60P_4	AN9	NC

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
5	IO_L50P_5	AG22	
5	IO_L49N_5	AN29	
5	IO_L49P_5	AN28	
5	IO_L30N_5	AK24	
5	IO_L30P_5	AK25	
5	IO_L29N_5	AH23	
5	IO_L29P_5	AH22	
5	IO_L28N_5	AP31	
5	IO_L28P_5	AP30	
5	IO_L27N_5/VREF_5	AH24	
5	IO_L27P_5	AH25	
5	IO_L26N_5	AF22	
5	IO_L26P_5	AF23	
5	IO_L25N_5	AM27	
5	IO_L25P_5	AM26	
5	IO_L24N_5	AL27	
5	IO_L24P_5	AL26	
5	IO_L23N_5	AH26	
5	IO_L23P_5	AJ25	
5	IO_L22N_5	AN31	
5	IO_L22P_5	AN30	
5	IO_L21N_5/VREF_5	AK26	
5	IO_L21P_5	AK27	
5	IO_L20N_5	AG23	
5	IO_L20P_5	AF24	
5	IO_L19N_5	AM33	
5	IO_L19P_5	AN32	
5	IO_L06N_5	AJ27	
5	IO_L06P_5	AJ26	
5	IO_L05N_5/VRP_5	AE22	
5	IO_L05P_5/VRN_5	AE23	
5	IO_L04N_5	AM28	
5	IO_L04P_5/VREF_5	AM29	
5	IO_L03N_5/D4/ALT_VRP_5	AK28	
5	IO_L03P_5/D5/ALT_VRN_5	AL29	
5	IO_L02N_5/D6	AG24	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
5	IO_L02P_5/D7	AG25	
5	IO_L01N_5/RDWR_B	AL30	
5	IO_L01P_5/CS_B	AM31	
6	IO_L01P_6	AE24	
6	IO_L01N_6	AD25	
6	IO_L02P_6/VRN_6	AJ30	
6	IO_L02N_6/VRP_6	AH30	
6	IO_L03P_6	AL32	
6	IO_L03N_6/VREF_6	AK32	
6	IO_L04P_6	AF25	
6	IO_L04N_6	AE25	
6	IO_L05P_6	AJ31	
6	IO_L05N_6	AK31	
6	IO_L06P_6	AH29	
6	IO_L06N_6	AG29	
6	IO_L19P_6	AG26	
6	IO_L19N_6	AF26	
6	IO_L20P_6	AL33	
6	IO_L20N_6	AK33	
6	IO_L21P_6	AJ32	
6	IO_L21N_6/VREF_6	AH32	
6	IO_L22P_6	AG28	
6	IO_L22N_6	AF28	
6	IO_L23P_6	AG30	
6	IO_L23N_6	AF30	
6	IO_L24P_6	AF29	
6	IO_L24N_6	AE29	
6	IO_L25P_6	AF27	
6	IO_L25N_6	AE27	
6	IO_L26P_6	AL34	
6	IO_L26N_6	AK34	
6	IO_L27P_6	AE28	
6	IO_L27N_6/VREF_6	AD28	
6	IO_L28P_6	AE26	
6	IO_L28N_6	AD26	

Table 12: FF1152 BGA — XC2V3000, XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V3000
NA	GND	B34	
NA	GND	B33	
NA	GND	B20	
NA	GND	B15	
NA	GND	B2	
NA	GND	B1	
NA	GND	A33	
NA	GND	A32	
NA	GND	A27	
NA	GND	A8	
NA	GND	A3	
NA	GND	A2	

Notes:

1. See Table 4 for an explanation of the signals available on this pin.

Table 13: FF1517 BGA — XC2V4000, XC2V6000, and XC2V8000

Bank	Pin Description	Pin Number	No Connect in the XC2V4000	No Connect in the XC2V6000
7	IO_L74P_7	U31		
7	IO_L74N_7	T31		
7	IO_L73P_7	R38		
7	IO_L73N_7	T38		
7	IO_L72P_7	T33		
7	IO_L72N_7	U33		
7	IO_L71P_7	U30		
7	IO_L71N_7	T30		
7	IO_L70P_7	R37		
7	IO_L70N_7	T37		
7	IO_L69P_7/VREF_7	R36		
7	IO_L69N_7	T36		
7	IO_L68P_7	T32		
7	IO_L68N_7	R32		
7	IO_L67P_7	P39		
7	IO_L67N_7	R39		
7	IO_L60P_7	R35		
7	IO_L60N_7	T35		
7	IO_L59P_7	U28		
7	IO_L59N_7	T28		
7	IO_L58P_7	N37		
7	IO_L58N_7	P37		
7	IO_L57P_7/VREF_7	R34		
7	IO_L57N_7	T34		
7	IO_L56P_7	T29		
7	IO_L56N_7	R29		
7	IO_L55P_7	M39		
7	IO_L55N_7	N39		
7	IO_L54P_7	N36		
7	IO_L54N_7	P36		
7	IO_L53P_7	R30		
7	IO_L53N_7	P30		
7	IO_L52P_7	M38		
7	IO_L52N_7	N38		
7	IO_L51P_7/VREF_7	P33		
7	IO_L51N_7	R33		